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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
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09/714,373

11/16/2000

David J. Alcoe

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08/01/2003

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EXAMINER

LINDINGER, MICHAEL L

ART UNIT

PAPER NUMBER

2841

DATE MAILED: 08/01/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

**Office Action Summary**

Application No.

09/714,373

Applicant(s)

ALCOE, DAVID J.

Examiner

Michael L. Lindinger

Art Unit

2841

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 16 May 2003.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 1,3-20 and 22-44 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☒ Claim(s) 1,3-19 and 37-41 is/are allowed.
- 6) ☒ Claim(s) 20,22-36 and 42-44 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) ☐ The proposed drawing correction filed on \_\_\_\_\_ is: a) ☐ approved b) ☐ disapproved by the Examiner.
- If approved, corrected drawings are required in reply to this Office action.
- 12) ☐ The oath or declaration is objected to by the Examiner.

**Priority under 35 U.S.C. §§ 119 and 120**

- 13) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
- ☐ Certified copies of the priority documents have been received.
  - ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- \* See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).
- a) ☐ The translation of the foreign language provisional application has been received.
- 15) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

**Attachment(s)**

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449) Paper No(s) \_\_\_\_\_.
- 4) ☐ Interview Summary (PTO-413) Paper No(s) \_\_\_\_\_.
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: \_\_\_\_\_.

### DETAILED ACTION

This action is in response to an Appeal brief filed May 16, 2003. The arguments in the Appeal Brief were found to be persuasive.

### ***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

1. Claims 20, 22, 26, 28, 31-36, 43-44 are rejected under 35 U.S.C. 103(a) as being unpatentable over Appelt U.S. Patent No. 5,900,675 in view of Lee U.S. Patent No. 6,050,832. Regarding Claims 20 and 43, Appelt teaches a connector system comprising a first substrate 620 of a first coefficient of thermal expansion, a second substrate 630 of a second coefficient of thermal expansion, a flexible connector 610/640, at least three contacts 612, 613 formed on a first surface of the substrate, and at least three contacts 631-634 formed on a second surface of the substrate, wherein select contacts on the first surface of the substrate are alternately offset from select contacts on the second surface of the substrate, wherein the coefficient of thermal expansion of the connector is midway between the first and second coefficient of thermal expansion of the first and second substrates, respectively (Col. 4, lines 8+; Col. 5, lines 58+; Col. 6, lines 1+; FIG. 6). Appelt does not explicitly teach at least three alternately offset contacts from a

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neutral point. Lee teaches an apparatus comprising a first substrate 14, a second substrate 10, a flexible connector 218 attached between the first and second substrates by a plurality of contacts on a first and second surface of the connector, wherein all of the contacts on the first and second surfaces alternate in respect to each other. This statement of "all of the contacts" would also encompass the limitation of "at least three contacts" and also the limitation of "at least three contacts in succession" (Col. 6, lines 63+; Col. 7, lines 1+; FIG. 3B). Lee teaches the general principle of alternating contacts in order to reduce stress within a multiple substrate and connector arrangement; however, Lee does not explicitly teach the details of that arrangement. Appelt teaches an electronic device wherein the connector comprises a laminate material, as well as the features included in the following rejections. It would have been obvious to a person skilled in the art at the time of the invention to provide additional contacts to the Appelt reference arranged in an offsetting manner to further reduce thermal expansion with the substrates. By utilizing common material in forming the connector and contacts, the conductivity will only increase as is expected when those materials are used.

Regarding Claim 22 and 44, Appelt teaches a connector system wherein the laminate material comprises a core, a compliant, dielectric material surrounding the core, and a solder mask (Col. 5, lines 58+; Col. 6, lines 1+; Col. 7, lines 1+; FIG. 6).

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Regarding Claim 26, Appelt teaches a connector system wherein the core comprises a material selected from the group consisting of copper-invar-copper, copper, stainless steel, nickel, iron, and molybdenum (Col. 6, lines 1+; Col. 7, lines 1+; FIG. 6).

Regarding Claim 28, Appelt teaches a connector system wherein the contacts comprise ball grid array connections (Col. 5, lines 58+; Col. 6, lines 1+).

Regarding Claims 31-36, the combination of the Appelt and Lee teachings inherently possess the methods of fabricating an electronic device and connector system and the corresponding mounting and assembling steps needed to construct the apparatus.

2. Claims 23-25 are rejected under 35 U.S.C. 103(a) as being unpatentable over Appelt U.S. Patent No. 5,900,675 in view of Lee U.S. Patent No. 6,050,832 in further view of Nguyen U.S. Patent No. 5,477,933. Regarding Claims 23-24, as described in the previous rejections above, the combination of Appelt and Lee teaches a laminate material, but not a laminate material with through holes. Nguyen teaches a laminate material with plated through holes 19 that provide electrical connection between at least one contact on the first surface 12 and one contact on the second surface 23 (Col. 3, lines 25+; FIG. 1, 3). It would be obvious to a person skilled in the art to provide the laminate material within the application through holes in order to provide electrical connection between the two surfaces. By connecting the through holes by a conductive

path, the solder contacts are provided increased strength and durability in protection against detachment as well.

Regarding Claim 25, Appelt teaches an electronic device with a connection layer. Appelt does not teach a ground shield over the connection layer. It would be obvious to a person skilled in the art to include a ground shield over the connection layer in the present application in order to provide additional impedance control for the apparatus. By definition, a ground or ground shield protects against any type of static discharge or a surge in current, therefore including a ground shield to the current application does not constitute a patentable improvement to the invention.

3. Claim 27 is rejected under 35 U.S.C. 103(a) as being unpatentable over Appelt U.S. Patent No. 5,900,675 in view of Lee U.S. Patent No. 6,050,832 in further view of Distefano U.S. Patent No. 6,309,915 B1. Regarding Claim 27, as mentioned in previous rejections above, the combination of Appelt and Lee teaches a dielectric layer, but does not teach a dielectric layer comprising polyimide. Distefano teaches a dielectric layer comprising polyimide (Col. 8, lines 55+; Col. 10, lines 17+). It would be obvious to a person skilled in the art to fabricate the dielectric layer for the current application out of polyimide. By choosing to have the dielectric layer comprising polyimide, the flexibility of the dielectric layer is increased and done so with a common polymeric material such as polyimide.

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4. Claims 29-30 and 42 are rejected under 35 U.S.C. 103(a) as being unpatentable over Appelt U.S. Patent No. 5,900,675 in view of Lee U.S. Patent No. 6,050,832 in further view of Sheppard U.S. Patent No. 6,284,569 B1. Regarding Claims 29-30, the combination of Appelt and Lee does not teach a stiffener frame. Sheppard teaches a stiffener frame 100 providing stiffening for an integrated circuit package further comprising a stiffener frame that is attached to and surrounds the perimeter of a substrate or connector, wherein the stiffener is adhesively or removably attached to the substrate, wherein the stiffener frame comprises a material selected from the group consisting of: plastic, metal, and ceramic (Col. 1, lines 57+, Col. 2, lines 6+). It would be obvious to a person skilled in the art to include a stiffener frame to the Appelt/Lee combination in a manner to not only insure a more rigid and secure electronic device, but to also act as a heat sink in the thermal dissipation of excess heat from the chip package. It can be assumed that as long as the general structure, which comprising the stiffener adhesively attached to a planar laminate by means of an acrylic adhesive material, then the properties of a heat sink will be achieved. Also, by including a stiffener frame, the chance for detachment of substrates between one another and overall damage due to handling is decreased. Regarding Claim 42, the teachings of the Prior Art not only teach an electronic device, but also inherently possess the method of manufacturing the electronic device.

***Prior Art***

1. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

- Jimarez U.S. Patent No. 6,191,952 B1 discloses a flip-chip electronic package comprising a compliant surface layer included on an interconnect carrier including a solder mask, a chip, a substrate, or printed circuit board, and solder balls arranged in a ball grid array to connect the chip to the carrier to the substrate.
- Susko U.S. Patent No. 6,177,728 B1 discloses an integrated circuit chip device comprising a chip, a carrier comprising a thermoplastic material layer, a glass filled epoxy layer, and an elastic layer, a printed circuit board, and solder balls arranged in a ball grid array to connect the chip to the carrier to the printed circuit board.
- Caletka U.S. Patent No. 6,104,093 discloses a thermally enhanced flip chip package comprising a chip and a laminate substrate electrically connected to the chip by means of solder balls.



- Iwasaki U.S. Patent No. 5,834,848 discloses an electronic device and semiconductor package comprising substrates of different coefficients of thermal expansion values.
- Kamath U.S. Patent No. 6,317,331 B1 discloses a wiring substrate with a thermal insert, wherein the insert has a different coefficient of thermal expansion value than the substrate that it is inserted to, thereby reducing the expansion of the substrate when under environmental conditions.
- Jackson U.S. Patent No. 6,333,563 B1 discloses an electrical interconnection package and method thereof comprising multiple substrates with contacts arranged in an alternating pattern.
- Sylvester U.S. Patent No. 6,014,317 discloses a chip package mounting structure for controlling warp of electronic assemblies due to thermal expansion effects.

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***Allowable Subject Matter***

1. Claims 1, 3-19, and 37-41 are allowed.

***Conclusion***

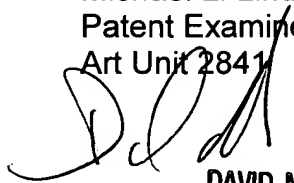
Any inquiry concerning this communication or earlier communications from the examiner should be directed to Michael L. Lindinger whose telephone number is (703) 305-0618. The examiner can normally be reached on Monday-Thursday (7:30-6).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David Martin can be reached on (703) 308-3121. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 305-3431 for regular communications and (703) 305-3431 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

MLL  
July 23, 2003

Michael L. Lindinger  
Patent Examiner  
Art Unit 2841



DAVID MARTIN  
SUPERVISORY PATENT EXAMINER  
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